



Material Content Data Sheet



Sales Product Name		SPU01N60C3		Issued		26. September 2017		
MA#		MA000851398						
Package		PG-TO251-3-21		Weight*		349.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.893	0.26	0.26	2557	2557
leadframe	non noble metal	tin	7440-31-5	0.273	0.08		782	
	non noble metal	copper	7440-50-8	181.882	52.07	52.15	520739	521521
wire	non noble metal	aluminium	7429-90-5	0.495	0.14	0.14	1417	1417
encapsulation	organic material	carbon black	1333-86-4	1.363	0.39		3903	
	inorganic material	antimonytrioxide	1309-64-4	2.850	0.82		8160	
	plastics	brominated resin	-	3.222	0.92		9225	
	plastics	epoxy resin	-	23.545	6.74		67411	
	inorganic material	silicondioxide	60676-86-0	92.941	26.61	35.48	266096	354795
leadfinish	non noble metal	tin	7440-31-5	3.976	1.14	1.14	11382	11382
plating	non noble metal	nickel	7440-02-0	0.344	0.10	0.10	985	985
solder	noble metal	silver	7440-22-4	0.033	0.01		95	
	non noble metal	tin	7440-31-5	0.026	0.01		76	
	non noble metal	lead	7439-92-1	1.262	0.36	0.38	3612	3783
heatspreader	non noble metal	iron	7439-89-6	0.036	0.01		104	
	inorganic material	phosphorus	7723-14-0	0.011	0.00		31	
	non noble metal	copper	7440-50-8	36.124	10.34	10.35	103425	103560
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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